Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
S1	174897	"438"/\$.ccls.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/01/08 15:15
S2	188	S1 and under near bump near metallization	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/08/25 15:21
S3	48	S2 and solder near bump and resin	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/08/25 15:57
S4		(("20030203049") or ("6730617")). PN.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2007/01/08 10:45
S5	2	("6897089").PN.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2007/01/08 10:46
S6	6	S4 or S5	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/01/08 10:46
. S7		S6 and polymer and bond same pad	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/01/08 10:50
58	0	polymer and (bond near5 pad) and (inprint\$3 same polymer) and (solder near4 bump) and passivation near10 polymer	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/01/08 10:54

S9	0	polymer and (bond near5 pad) and	US-PGPUB;	OR	ON	2007/01/08 10:54
		(inprint\$3 same polymer) and (solder near4 bump)	USPAT; USOCR; EPO; JPO; DERWENT;			2557,01705 10.54
		• ,	IBM_TDB	! :		
S10	0	polymer and (bond near5 pad) and (imprint\$3 same polymer) and (solder near4 bump) and passivation near10 polymer	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR .	ON	2007/01/08 10:54
S11	15	polymer and (bond near5 pad) and (imprint\$3 same polymer) and (solder near4 bump)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/01/08 11:16
S12	5	(US-20060211171-\$ or US-20060073344-\$ or US-20050221597-\$ or US-20050142345-\$).did. or (US-20050221597-\$).did.	US-PGPUB; DERWENT	OR	ON	2007/01/08 11:15
S13	5	S12 and polymer and (bond near5 pad) and (imprint\$3 same polymer) and (solder near4 bump)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/01/08 11:42
S14	13	(US-20040142575-\$ or US-20030146095-\$ or US-20040209355-\$ or US-20060216740-\$ or US-20040115696-\$ or US-20050142345-\$ or	US-PGPUB; USPAT	OR	ON	2007/01/08 11:42
	·	US-20060073344-\$ or US-20060211171-\$).did. or (US-6946322-\$ or US-7060224-\$ or US-6569382-\$ or US-6706473-\$ or US-6652808-\$).did.				
S15	13	S14 and polymer and (bond near5 pad) and (imprint\$3 same polymer) and (solder near4 bump)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR .	ON	2007/01/08 11:49

S16	0	S14 and (vibration or stamp or press or vibratory) same pad	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/01/08 11:58
S17	1	S11 and (vibration or stamp or press or vibratory) same pad	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/01/08 11:59
S18	1	(US-20050221597-\$).did.	US-PGPUB	OR	ON	2007/01/08 11:59
S19	1	S18 and (vibration or stamp or press or vibratory) same pad	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON .	2007/01/08 12:00
S20		S18 and (vibration or stamp or press or vibratory) same pad and thermal same load	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/01/08 12:01
S21	13	(("5753529") or ("6642081") or ("20040048459") or ("6255126") or ("6746938") or ("20030003724") or ("5674758")).PN.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2007/01/08 15:15
S22	13	(("5753529") or ("6642081") or ("20040048459") or ("6255126") or ("6746938") or ("20030003724") or ("5674758")).PN.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2007/01/08 22:51
S23	13	(("5753529") or ("6642081") or ("20040048459") or ("6255126") or ("6746938") or ("20030003724") or ("5674758")).PN.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2007/01/09 10:10
\$24	7	S23 and conduct\$3 same (via or hole or post)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/01/09 10:25

S25	2	("20030203623").PN.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2007/01/09 10:14
S26	2	S25 and conduct\$3 same (via or hole or post)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/01/09 10:14
S27	5	S24 and post	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/01/09 11:04
S28	4	S27 and dielectric	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/01/09 11:30
S29	2	S26 and dielectric	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON :	2007/01/09 11:30
530	195157	"438"/\$.ccls.	US-PGPÜB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/01/09 11:33
S31	26	S30 and conduct\$3 same (post or column or pillar or (upright near3 support)) and substrate same front same back and dielectric same ((layer or (inter near2 layer)) same front same back)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/01/09 16:30
S32	228	conduct\$3 same (post or column or pillar or (upright near3 support)) and substrate same front same back and dielectric same ((layer or (inter near2 layer)) same front same back)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/01/09 14:22

S33	28	(US-20020024498-\$ or	US-PGPUB;	OR	ON	2007/01/09 15:53
		US-20020012076-\$ or	USPAT			
		US-20020119622-\$ or US-20030197468-\$ or	İ	<b>[</b>	:	
		US-20050197408-\$ 07	1		i	
j		US-20060246295-\$ or	!	) :		
1		US-20030011307-\$ or		,		
		US-20050023978-\$ or	1.			
1	,	US-20020195939-\$ or	1	}		
		US-20040173890-\$ or		1		
		US-20020027022-\$ or				
		US-20010050534-\$).did. or (US-6184848-\$ or US-5990854-\$ or				
		US-5745086-\$ or US-6278422-\$ or		!		
		US-6747614-\$ or US-4052705-\$ or	[ 			
+		US-7145524-\$ or US-6639355-\$ or		E		
		US-6784615-\$ or US-6657620-\$ or	į.	1	!	!
-		US-6979950-\$ or US-7071621-\$ or		İ		
		US-6118214-\$ or US-6538333-\$ or		 		
		US-6890829-\$ or US-6908856-\$). did.				
						2007/24/25 := ==
S34	28	S33 and conduct\$3 same (post or	US-PGPUB;	OR	ON	2007/01/09 17:56
		column or pillar or (upright near3	USPAT; USOCR;			
1		support)) and substrate same front same back and dielectric same	EPO; JPO;	1		
	1	((layer or (inter near2 layer)) same	DERWENT;		İ	
		front same back)	IBM_TDB		İ	
S35	28	S33 and dielectric same ((layer or	US-PGPUB;	OR	ON	2007/01/09 17:52
		(inter near2 layer)) same front	USPAT;	I		
		same back)	USOCR;			
		• •	EPO; JPO;	!		
			DERWENT; IBM_TDB	!		
ĺ			_			
S36	23	S33 and dielectric same ((layer or	US-PGPUB;	OR	ON	2007/01/09 17:59
		(inter near2 layer)) same front	USPAT; USOCR;			
		same back) same substrate	EPO; JPO;	!	1 .	i
1		;	DERWENT;			
1			IBM_TDB			
S37	28	S33 and conduct\$3 same (post or	US-PGPUB;	OR	ON	2007/01/09 18:18
337	20	column or pillar or (upright near3	USPAT;			
		support))	USOCR;			
			EPO; JPO;			
			DERWENT;			
į		 	IBM_TDB			
S38	23		US-PGPUB;	OR	ON	2007/01/09 17:59
		(inter near2 layer)) same front	USPAT;			
		same back) same substrate	USOCR;		1	!
	•		EPO; JPO;			-
t		:	DERWENT; IBM_TDB	1		
		l	ם סוים ביים	· 	<u> </u>	

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S39	2 ·	(US-20040173890-\$).did. or (US-6890829-\$).did.	US-PGPUB; USPAT	OR	ON	2007/01/09 18:05
\$40		S39 and conduct\$3 same (post or column or pillar or (upright near3 support)) and dielectric same ((layer or (inter near2 layer)) same front same back) same substrate	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/01/09 18:49
S41	2	(US-20040173890-\$).did. or (US-6890829-\$).did.	US-PGPUB; USPAT	OR	ON	2007/01/09 21:53
S42	. 2	S41 and conduct\$3 same (post or column or pillar or (upright near3 support)) and dielectric same ((layer or (inter near2 layer)) same front same back) same substrate	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/01/09 22:01
S43	2	S42 and metal	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/01/09 21:55
S44		S42 and (metal or metalizing or metalatization)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/01/09 21:55
S45	2	S41 and conduct\$3 same (post or column or pillar or (upright near3 support)) same substrate	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/01/09 22:10
S46	1	(US-20050221597-\$).did.	US-PGPUB	OR	ON	2007/01/10 12:03
S47	0	S46 and conduct\$3 same (post or column or pillar or (upright near3 support)) same substrate	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/01/09 22:10
S48	195157	"438"/\$.ccls.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR 	ON	2007/01/09 22:15

S49	674	S48 and conductive same post same substrate	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/01/09 22:18
S50		S49 and front same side same substrate and back same (side or area) same substrate'	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/01/10 10:08
S51		S49 and front same side same substrate and back same (side or area) same substrate	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/01/09 22:18
S52	6	S48 and conductive same post same substrate and front same side same substrate same post and back same (side or area) same substrate same post	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/01/09 22:20
S53	34	conductive same post same substrate and front same side same substrate same post and back same (side or area) same substrate same post	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ΟN	2007/01/09 22:26
S54		conductive same (post or via) same substrate and front same side same substrate same (post or via) and back same (side or area) same substrate same post and stack	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/01/09 22:27
S55	55	conductive same (post or via) same substrate and front same substrate same (post or via) and back same substrate same post and stack	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/01/09 22:36
S56	46	conductive same (post or column or support or pillar or prong or connector) same substrate and front same substrate same (post or column or support or pillar or prong or connector) and back same substrate same post and stack	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/01/09 22:38

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S57	124	conductive same (post or column or support or pillar or prong or	US-PGPUB; USPAT;	OR	ON	2007/01/09 23:00
		connector) same substrate and	USOCR;	!		
		front same substrate same (post or	EPO; JPO;			
	]	column or support or pillar or prong	DERWENT;	!		
		or connector) and back same	IBM_TDB	[		 
		substrate same post	!			 I
S58	4	(US-20040201095-\$ or	US-PGPUB;	OR	ON ·	2007/01/09 22:38
		US-20020155692-\$).did. or	USPAT			
i		(US-6124198-\$ or US-6538333-\$).		1		
		did.				

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S59	124	(US-20020097962-\$ or	US-PGPUB;	OR	ON	2007/01/09 22:40
:		US-20020039464-\$ or	USPAT;			
' !		US-20020028045-\$ or	USOCR;			
		US-20030148598-\$ or	EPO; JPO;	1		
;		US-20060281303-\$ or	DERWENT;		İ	
1	•	US-20060281292-\$ or	IBM_TDB			
		US-20060278996-\$ or				
		US-20060278993-\$ or	-			
		US-20060278992-\$ or		1		
		US-20060278988-\$ or				
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		US-20060278966-\$ or	1	1		.
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1		US-20060281219-\$ or		1		
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		US-20060278994-\$ or		1		
		US-20060278989-\$ or		ļ		!
		US-20060278986-\$ or				
i	•	US-20060250335-\$ or				
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		US-20030103836-\$ or			1	
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	,	US-20040023494-\$).did. or			1.	
1/17/07	2:43:37 PM	-(US-6845184-\$-or-US-6785447-\$-or-	<del> </del>	-	† <del></del>	Page 9
C:\Docu	ments and Se	US-6706546-\$ or US-6690845-\$ or US-6690845-\$ or US-6690845-\$ or US-6690845-\$ or US-6690845-\$ or	rkspaces\1081	5561.wsp	Ì	, 090 %
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S60	124	S59 and front same substrate same	US-PGPUB;	OR	ON	2007/01/09 22:42
300		(post or column or support or pillar or prong or connector) and back same substrate same(post or column or support or pillar or prong or connector)	USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB		OIV .	2007/01/09 22:42
S61	113	S59 and front same substrate same (post or column or support) and back same substrate same(post or column or support)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/01/10 10:07
S62	9	S48 and front same substrate same post and back same substrate same post and Damascene	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/01/09 22:47
S63	74	conductive same (post or column or plug) same substrate and front same substrate same (post or column or plug) and back same substrate same post	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/01/09 23:18
S64	9 .	(US-20020160598-\$ or US-20020155692-\$ or US-20040173890-\$ or US-20020027022-\$).did. or (US-6569762-\$ or US-6538333-\$ or US-6444576-\$ or US-6020217-\$ or US-6124198-\$).did.	US-PGPUB; USPAT	OR	ON	2007/01/09 23:17
S65	9	S64 and conductive same (post or column or plug) same substrate and front same substrate same (post or column or plug) and back same substrate same post	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/01/10 00:08
S66	3	(US-20020160598-\$ or US-20040173890-\$).did. or (US-6538333-\$).did.	US-PGPUB; USPAT	. OR	ON	2007/01/10 00:08
S67	3	S66 and conductive same (post or column or plug) same substrate and front same substrate same (post or column or plug) and back same substrate same post	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/01/10 00:14

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S68	3	S67 and metal	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/01/10 00:14
S69	3	S67 and metal same substrate	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/01/10 00:17
S70		S67 and metal same substrate same layer	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/01/10 00:15
S71	3	(US-20020160598-\$ or US-20040173890-\$).did. or (US-6538333-\$).did.	US-PGPUB; USPAT	OR .	ON	2007/01/10 09:59
S72	3	S71 and conductive same (post or column or plug) same substrate and front same substrate same (post or column or plug) and back same substrate same post	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/01/10 09:59
S73	3	S72 and metal same substrate	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR .	ON	2007/01/10 09:59
S74	3	S73 and front same substrate same (post or column or support) and back same substrate same(post or column or support)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/01/10 10:07
S75	3	S74 and front same side same substrate and back same (side or area) same substrate	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/01/10 10:36
S76	3	S71 and metal	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/01/10 10:37

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S77	3	S71 and metal and substrate	US-PGPUB; USPAT;	OR	ON	2007/01/10 10:46
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			IBM_TDB			,
S78	3	S71 and metal same substrate	US-PGPUB;	OR	ON	2007/01/10 12:10
1			USPAT;		l	·
			USOCR; EPO; JPO;			
			DERWENT;	!		
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S79	. 3	S71 and metal	US-PGPUB; USPAT;	OR	ON	2007/01/10 10:46
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1			EPO; JPO;			
		1	DERWENT;	į	1	
S80	2	("20030203623").PN.	IBM_TDB US-PGPUB;	OR.	OFF	2007/01/10 12:03
; 500	. 2	( 20030203023 ).FN.	USPAT;	UK.	OFF	2007/01/10 12.03
; ;			USOCR;	•		. !
1			EPO; JPO;	!		
1			DERWENT; IBM_TDB		!	
: S82	2	S80 and post	US-PGPUB;	OR	ON ·	2007/01/10 13:17
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			USOCR;			
			EPO; JPO; DERWENT;			
			IBM_TDB			
S83	3	S71 and conduct\$4 same substrate	US-PGPUB;	OR	ON	2007/01/10 12:55
:			USPAT;	:		
			EPO; JPO;	:	i	
			DERWENT;	1		
			IBM_TDB			
S84	2	S80 and post and dielectric	US-PGPUB;	OR	ON	2007/01/10 12:20
i			USPAT; USOCR;			
			EPO; JPO;			Í
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S85	3	S83 and post and dielectric	US-PGPUB; USPAT;	OR	ON	2007/01/10 12:20
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S86	3	S71 and post and dielectric	US-PGPUB; USPAT;	OR	ON	2007/01/10 12:21
:			USOCR; EPO; JPO; DERWENT; IBM_TDB	, , , ,		
S88	3	S71 and dielectric	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/01/10 12:21
S89	3	S71 and (glass or powder or dielectric or insulat\$4)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/01/10 12:58
S90	3	S71 and (glass or powder or dielectric)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/01/10 13:07
S91	3	S71 and (glass or powder or dielectric or ceramic)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/01/10 19:35
S92	2	S80 and post and dielectric	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/01/10 13:18
: S93	2	("20040266141").PN.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2007/01/10 19:37
\$94	0	S93 and second same laser	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/01/10 19:37

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S95	0	S93 and laser	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR .	ON	2007/01/10 19:37
S96	2	("20040266147").PN.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2007/01/10 19:37
S97	1	S96 and second same laser	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/01/10 19:38
S98	0	S96 and second same laser same directly	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/01/10 19:38
S99	0	S96 and directly	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/01/10 19:38